

Title (en)

Composition for preparing organic insulator

Title (de)

Zusammensetzung zur Darstellung eines organischen Insulators

Title (fr)

Composition pour la préparation d'un isolateur organique

Publication

**EP 1524299 A1 20050420 (EN)**

Application

**EP 04256183 A 20041006**

Priority

KR 20030071775 A 20031015

Abstract (en)

Disclosed is a composition for preparing an organic insulator, the composition comprising (i) at least one organic-inorganic hybrid material; (ii) at least one organometallic compound and/or organic polymer; and (iii) at least one solvent for dissolving the above two components, so that an organic insulator using the same has a low threshold voltage and driving voltage, and high charge carrier mobility and Ion/Ioff ratio, thereby enhancing insulator characteristics. Further, the preparation of organic insulating film can be carried out by wet process, so that simplification of the process and cut of cost are achieved. <IMAGE>

IPC 1-7

**C08L 83/06**; H01L 21/3205; H01L 21/316

IPC 8 full level

**H01L 21/31** (2006.01); **C08G 77/04** (2006.01); **C08K 5/05** (2006.01); **C08L 83/04** (2006.01); **C08L 83/06** (2006.01); **C08L 101/00** (2006.01); **C09D 5/25** (2006.01); **C09D 183/04** (2006.01); **C09D 183/06** (2006.01); **H01L 21/312** (2006.01); **H01L 21/316** (2006.01); **H01L 21/3205** (2006.01); **H01L 29/786** (2006.01); **H01L 51/05** (2006.01); **H01L 51/30** (2006.01); **H01L 51/40** (2006.01); **C08K 5/057** (2006.01); **C08K 5/56** (2006.01)

CPC (source: EP KR US)

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C-Set (source: EP US)

**C08L 83/04** + **C08L 2666/02**

Citation (search report)

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